External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.2438	90.0	5.202
	Lead alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.00135	0.5	0.0289
	Lead alloy	Silver (Ag)	7440-22-4	0.00677	2.5	0.1445
	Lead alloy	Antimony (Sb)	7440-36-0	0.01896	7.0	0.4046
			Subtotal	0.27088	100	5.78
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01196	100.0	0.25513
			Subtotal	0.01196	100	0.25513
Heat Spreader	Copper alloy	Phosphorous (P)	7723-14-0	0.01687	0.03	0.36
	Copper alloy	Iron (Fe)	7439-89-6	0.05624	0.1	1.2
	Copper alloy	Copper (Cu)	7440-50-8	56.16603	99.87	1,198.44
			Subtotal	56.23914	100	NaN
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.26538	100.0	27
			Subtotal	1.26538	100	27
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00562	0.03	0.12
	Copper alloy	Iron (Fe)	7439-89-6	0.01875	0.1	0.4
	Copper alloy	Copper (Cu)	7440-50-8	18.72201	99.87	399.48
			Subtotal	18.74638	100	400
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.05858	5.0	1.25
	Lead alloy	Silver (Ag)	7440-22-4	0.02929	2.5	0.625
	Lead alloy	Lead (Pb)	7439-92-1	1.08378	92.5	23.125
			Subtotal	1.17165	100	25
Isolator	Copper alloy	Phosphorous (P)	7723-14-0	0.00422	0.1	0.09
	Copper alloy	Aluminium Trioxide (Al2O3)	1344-28-1	3.86363	91.6	82.44
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.03796	0.9	0.81
	Copper alloy	Molybdenum (Mo)	7439-98-7	0.29526	7.0	6.3
	Copper alloy	Manganese (Mn)	7439-96-5	0.01687	0.4	0.36
			Subtotal	4.21794	100	90
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.26714	1.5	5.7
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	1.69186	9.5	36.1
	Filler	Silica fused	60676-86-0	15.67197	88.0	334.4
	Carbon Black	Carbon black	1333-86-4	0.17809	1.0	3.8
			Subtotal	17.80906	100	380
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.10826	100.0	2.31
			Subtotal	0.10826	100	2.31
Die	Doped silicon	Silicon (Si)	7440-21-3	0.15934	100.0	3.4
			Subtotal	0.15934	100	3.4
			Total	99.99999	100	NaN

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